



The DNA of tech™

Product Information Notification

Product Group: TC/Monday September 8, 2025/PIN-TC-009-2025-REV-0



Update moisture sensitivity caution MMB printout with 24 months calculated shelf life and corrections in accordance with J-STD-20 and J-STD-75

For further information, please contact your regional Vishay office.

CONTACT INFORMATION

Americas

David Bellomy

-

-

- United States -

Europe

Michel Bouvier

-

-

- France -

Asia

Falco Hung

-

-

- Hong Kong 528886

Description of Change: Added 24 months calculated shelf life at <30C and <70% Related humidity.

Added P6G process sensitivity level for package thickness $\geq 2.5\text{mm}$ according to J-STD-75.

Added 250C Peak body temperature for package thickness $\geq 2.5\text{mm}$ according to J-STD-20.

Vishay reserves the right to use both printout styles.

Reason for Change: Moisture sensitivity caution MMB printout update.

Expected Influence on Quality/Reliability/Performance: No.

Part Numbers/Series/Families Affected: T50*, T51*, T55*,

Vishay Brand(S): Vishay

Time Schedule:

Start Shipment Date: Wednesday October 15, 2025

Sample Availability: Upon Request.

Product Identification: N/A

Qualification Data: N/A

Issued By: Bruno Lima,

Current printout



Caution

This bag contains
**MOISTURE-SENSITIVE and
PROCESS SENSITIVE DEVICES**

LEVEL (MSL)

3

1. Calculated shelf life in sealed bag: 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)
Bag Seal Date: Refer to bar code label or lot number
2. Peak package body temperature: 260°C
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
 - a) Mounted within: 168 hours of factory conditions $< 30^{\circ}\text{C}/60\%$ RH, or
 - b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
 - a) Humidity Indicator Card reads $> 10\%$ for level 2a - 5a devices or $> 60\%$ for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$
 - b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J-STD-020

Note 2: Process Sensitivity Levels (PSLs) defined by ECIA/IPC/JEDEC J-STD-075

PROCESS SENSITIVE DEVICES

LEVEL (PSL)

R4G

PSL Additional Information: Time (tp) is 5 seconds



New printout (changes in yellow)



Caution

This bag contains
**MOISTURE-SENSITIVE and
PROCESS SENSITIVE DEVICES**

LEVEL (MSL)

3

1. Calculated shelf life in sealed bag:
 - a) 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)
 - b) 24 months at $< 30^{\circ}\text{C}$ and $< 70\%$ relative humidity (RH)Bag Seal Date: Refer to bar code label or lot number
2. Peak package body temperature:
 - a) 260°C : Package Thickness $< 2.5\text{ mm}$
 - b) 250°C : Package Thickness $\geq 2.5\text{ mm}$
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
 - a) Mounted within: 168 hours of factory conditions $< 30^{\circ}\text{C}/60\%$ RH, or
 - b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
 - a) Humidity Indicator Card reads $> 10\%$ for level 2a - 5a devices or $> 60\%$ for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$
 - b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Note 1: Level (MSL) and body temperature defined by IPC/JEDEC J-STD-020

Note 2: Process Sensitivity Levels (PSLs) defined by ECIA/IPC/JEDEC J-STD-075

PROCESS SENSITIVE DEVICES

LEVEL (PSL)

R4G	Package Thickness $< 2.5\text{ mm}$ PSL Additional Information: Time (tp) is 5 seconds
R6G	Package Thickness $\geq 2.5\text{ mm}$ PSL Additional Information: Time (tp) is 5 seconds

